

Tech-X Corporation invites you to visit us at Booth #705 at the [IEEE MTT 2010 International Microwave Symposium](#), May 23 - 28 in Anaheim.

We are proud to present our electromagnetic plasma simulation software, VORPAL (<http://vorpalltxcorp.com>). VORPAL 4.0 provides for the first time parallel and multi-core capability to the Windows platform (as with previous versions, VORPAL 4.0 also runs in parallel on the Linux and Macintosh platforms). Let VORPAL 4.0 help you take full advantage of your multi-core desktop computer. Other new capabilities include:

- cylindrical coordinates for electromagnetic simulation
- automated eigenfrequency and eigenmode extraction from time-domain simulation
- new secondary electron models that allow simulations of complex metallic and dielectric boundaries of arbitrary shape without stairsteps
- improved post-processing, including automated import into the VisIt software for advanced visualization